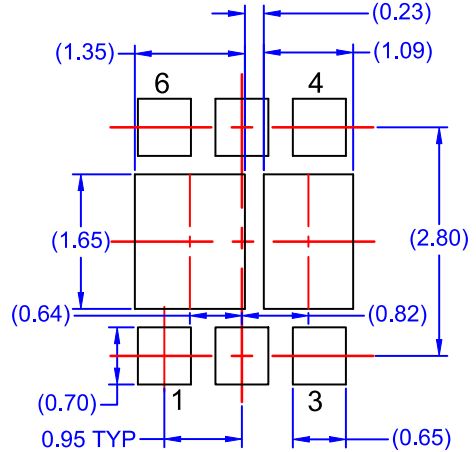
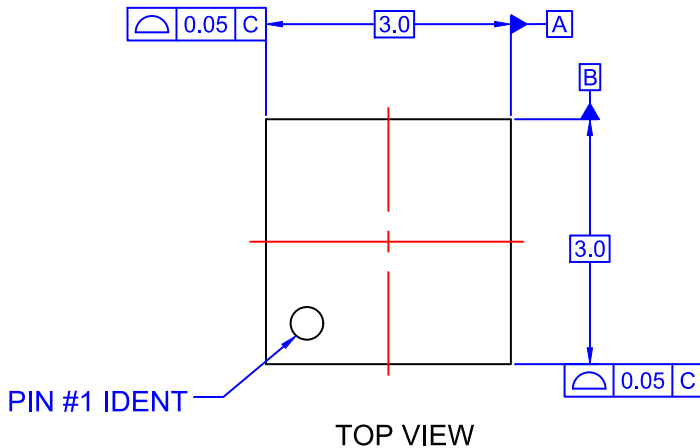


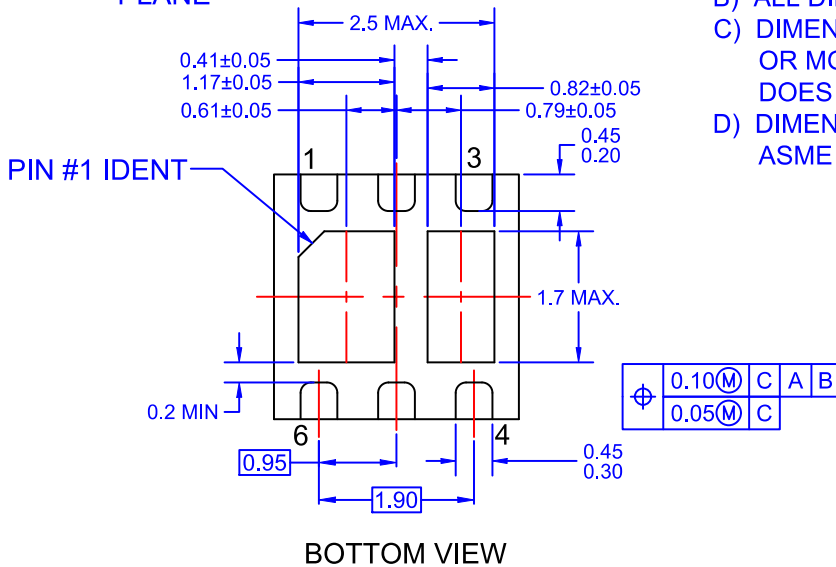
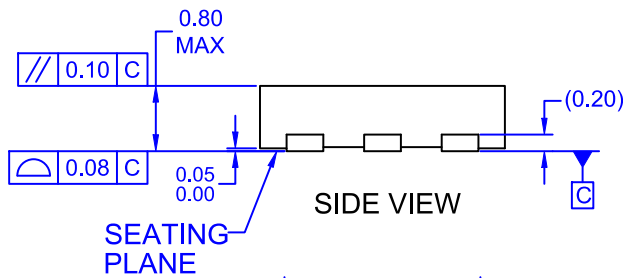


WDFN6 3x3, 0.95P
CASE 511DT
ISSUE O

DATE 31 DEC 2016



RECOMMENDED LAND PATTERN



- NOTES: UNLESS OTHERWISE SPECIFIED
A) CONFORMS TO JEDEC REGISTRATION, MO-229, VARIATION WEEA
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.

⊕	0.10(M)	C	A	B
	0.05(M)	C		

DOCUMENT NUMBER:	98AON13605G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WDFN6 3x3, 0.95P	PAGE 1 OF 2

